

# CMOS UV ERASABLE 524288-BIT READ ONLY MEMORY

### MBM27C512-15 MBM27C512-17

October 1987 Edition 1.0

# CMOS 524288 BIT UV ERASABLE AND ELECTRICALLY PROGRAMMABLE READ ONLY MEMORY

The Fujitsu MBM 27C512 is a high speed 524,288 bit static CMOS erasable and electrically reprogrammable read only memory (EPROM). It is especially well suited for application where rapid turn-around and/or bit pattern experimentation, and low-power consumption are important.

A 28-pin dual-in line package with a transparent lid and 32-Pad Leadless Chip Carrier (LCC) are used to package the MBM 27C512. The transparent lid allows the user to expose the device to ultraviolet light in order to erase the memory bit pattern previously programmed. At the completion of erasure, a new pattern can then be written into the memory.

The MBM 27C512 is fabricated using CMOS double polysilicon gate technology with single transistor stacked gate cells. It is organized as 65,536 words by 8 bits for use in microprocessor applications. Single +5V operation greatly facilitates its use in systems.

This specification is applied to "HW" version.

- CMOS power consumption Standby: 550μW/max.
   Active: 220mW/max.
- 65,536 words x 8 bits organization, fully decoded
- Single location programming
- Programmable utilizing the Quick Pro<sup>TM</sup> Algorithm
- No clocks required (fully static operation)
- TTL compatible inputs/outputs

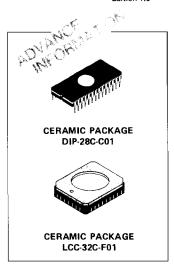
- Fast access time:
  - 150ns max. (MBM27C512-15) 170ns max. (MBM27C512-17)
- Three-state output with OR-tie capability
- Output Enable (OE) pin for simplified memory expansion
- Single +5V supply, ±10% tolerance
- Standard 28-pin Ceramic DIP: (Suffix: -Z)
- Standard 32-pad Ceramic LCC: (Suffix: -TV)

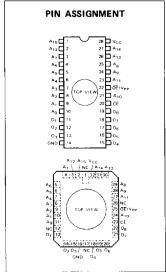
#### ABSOLUTE MAXIMUM RATINGS (See NOTE)

Rating	Symbol	Value	Unit
Temperature under Bias	TBIAS	~25 to +85	°C
Storage Temperature	T <sub>STG</sub>	-65 to +125	°C
All Inputs/Outputs Voltage with Respect to GND	V <sub>IN</sub> , V <sub>OUT</sub>	-0.6 to V <sub>CC</sub> +0.6	٧
Voltage on A <sub>9</sub> with Respect to GND	V <sub>A9</sub>	-0.6 to 13.5	v
V <sub>PP</sub> Voltage with Respect to GND	V <sub>PP</sub>	-0.6 to +14	٧
Supply Voltage with Respect to GND	V <sub>cc</sub>	-0.6 to +7	V

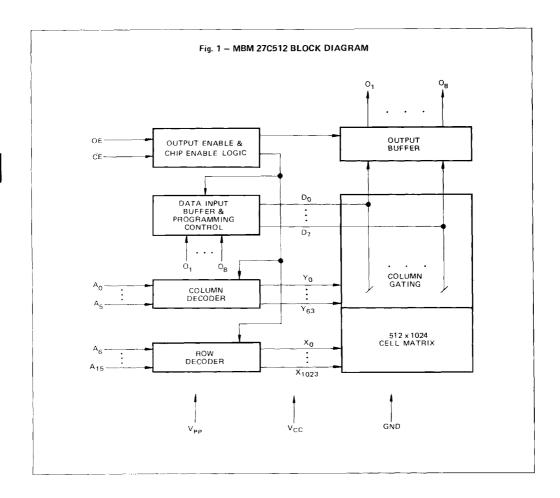
NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Quick ProTM is a trademark of FUJITSU LIMITED





This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.



## CAPACITANCE (TA = 25°C, f = 1MHz)

			Unit		
Parameter	Symbol	Min	Түр	Max	Unit
Input Capacitance (V <sub>IN</sub> = 0 V, except $\overline{OE}/V_{PP}$ )	C <sub>IN1</sub>	_	4	6	pF
OE/V <sub>PP</sub> Input Capacitance (V <sub>IN</sub> = 0 V)	C <sub>IN 2</sub>		-	20	pF
Output Capacitance (V <sub>OUT</sub> = 0 V)	Соит	_	8	12	pF

#### **FUNCTIONS AND PIN CONNECTIONS**

Function (Pin No.) Mode	Address Input (1~10, 21, 23~27)	Data I/O (11~13, 15~19)	CE (20)	ŌĒ/V <sub>PP</sub> (22)	V <sub>CC</sub> (28)	GND (14)
Read	A <sub>IN</sub>	D <sub>OUT</sub>	VIL	V <sub>IL</sub>	5V	GND
Output Disable	A <sub>IN</sub>	High-Z	VIL	V <sub>IH</sub>	5V	GND
Standby	Don't Care	High-Z	V <sub>IH</sub>	Don't Care	5V	GND
Program	A <sub>IN</sub>	D <sub>IN</sub>	VIL	12.5V	6V	GND
Program Verify	A <sub>IN</sub>	D <sub>out</sub>	VIL	V <sub>IL</sub>	6V	GND
Program Inhibit	Don't Care	High-Z	V <sub>IH</sub>	12.5V	6V	GND

## RECOMMENDED OPERATING CONDITIONS (Referenced to GND)

Parameter	Second and					
	Symbol	Min	Тур	Max	Unit	
V <sub>CC</sub> Supply Voltage	V <sub>cc</sub>	4.5	5.0	5.5	٧	
Input High Voltage	V <sub>IH</sub>	2.0		V <sub>CC</sub> +0.3	٧	
Input Low Voltage	VıL	-0.1		0.8	٧	
Operating Temperature	TA	0		70	°C	

## DC CHARACTERISTICS (Recommended operating conditions unless otherwise noted)

Parameter		Constant		Value				
		Symbol	Min	Тур	Max	Unit		
Input Load Current (V <sub>IN</sub> = 5.5 V)		_			10	μΑ		
Output Leakage Current (V <sub>OUT</sub>	= 5.5 V)	IILO			10	μΑ		
$V_{CC}$ Standby Current ( $\overline{CE} = V_{IH}$ )		I <sub>SB1</sub>			1	mA		
$V_{CC}$ Standby Current ( $\overline{CE} = V_{CC} \pm 0.3 \text{ V, } I_{OUT} = 0 \text{ mA}$	A)	I <sub>SB2</sub>		1	100	μΑ		
V <sub>CC</sub> Active Current (CE = V <sub>IL</sub> , I <sub>OUT</sub> = 0 mA)	150 ns 170 ns	l <sub>CC1</sub>		4	40 30	m A		
V <sub>CC</sub> Operation Current (f = 4 MHz, I <sub>OUT</sub> = 0 mA)		lccs		10	40	mA		
Output Low Voltage (I <sub>OL</sub> = 2.1 mA)		Vol			0.45	V		
Output High Voltage (I <sub>OH</sub> = -400 μA)		V <sub>OH1</sub>	2.4			V		
Output High Voltage (IOH = -100 µA)		V <sub>OH2</sub>	V <sub>CC</sub> -0.7			٧		

#### Fig. 2 - AC TEST CONDITIONS (INCLUDING PROGRAMMING)

Input Pulse Levels:

0.45V to 2.4V

Input Rise and Fall Times:

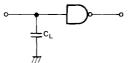
≤ 20 ns

Timing Measurement Reference Levels: 0.8V and 2.0V for inputs

0.8V and 2.0V for inputs 0.8V and 2.0V for outputs

Output Load:

1 TTL gate and C<sub>L</sub> = 100pF



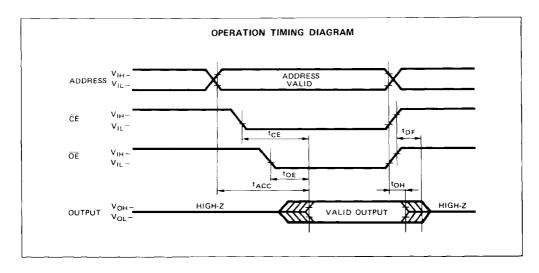
## AC CHARACTERISTICS

(Recommended operating conditions unless otherwise noted)

Parameter	Symbol	MBM 27C512-15			MBM 27C512-17			11.24
Parameter		Min	Тур	Max	Min	Тур	Max	Unit
Address Access Time*1	t <sub>ACC</sub>			150			170	ns
CE to Output Delay	t <sub>CE</sub>			150			170	ns
OE to Output Delay*1	t <sub>OE</sub>			60			70	ns
Address to Output Hold	t <sub>OH</sub>	0			0			ns
Output Enable High to Output Float*2	toF	0		60	0		60	ns

Notes:

- \*1  $\overline{OE}$  may be delayed up to  $t_{ACC} t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{ACC}$ .
  \*2  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$ , whichever occurs first.
- Output Float is defined as the point where data is no longer driven.



#### PROGRAMMING/ERASING INFORMATION

#### **PROGRAMMING**

Upon delivery from Fujitsu, or after each erasure (see Erasure section), the MBM 27C512 has all 524,288 bits in the "1", or high state. "0's" are loaded into the MBM 27C512 through the procedure of programming.

The MBM 27C512 is programmed with a fast programming algorithm designed by Fujitsu called Quick ProTM. The programming mode is entered when +12.5V and +6V are applied to VPP and V<sub>CC</sub> respectively, and CE is V<sub>IH</sub>. A 0.1μF capacitor between V<sub>PP</sub> and GND is needed to prevent excessive voltage transients which could damage the device. The address to be programmed is applied to the proper address pins. The 8 bit data pattern to be written is placed on the respective data output pins. The voltage levels should be standard TTL levels. When both the address and data are stable, a 1 ms programming

pulse is applied to  $\overline{CE}$  and after that one additional pulse which is 3 times as wide as previous pulse is applied to  $\overline{CE}$  to accomplish the programming.

Procedure of Quick  $Pro^{TM}$  (Refer to the attached flowchart.)

- 1) Set the start address (=G) at the address pins.
- 2) Set  $V_{CC} = 6V$ ,  $V_{PP} = 12.5V$  and  $\overline{CE} = V_{IH}$ .
- Clear the programming pulse counter (X ← 0).
- 4) Input data to respective pins.5) Apply ONE programming pulse
- 5) Apply ONE programming pulse (tpw = 1ms Typ.) to CE.
- 6) Increment the counter (X ← X+1).
- 7) Compare the number (=X) of applied programming pulse with 25 and then verify the programmed data. If programmed data is verified, go to the next step regardless of X value. If X = 25 and programmed data is not verified the

device fails. If X < 25 and programmed data is not verified, go back to the step 5).

- Apply one additional wide programming pulse to CE (3X ms).
- 9) Compare the address with an end address (=N). If the programmed address is the end address, proceed to the next step. If not, increment the address (G ← G+1) and then go to the step 3) for the next address.
- 10) Set V<sub>CC</sub> = V<sub>PP</sub> = 5V.
- 11) Verify the all programmed data. If the verification succeeds, the programming completes. If any programmed data is not the same as original data, the device fails.

A continuous  $\overline{TTL}$  low level should not apply to  $\overline{CE}$  input pin during the program mode ( $V_{PP} = 12.5V$  and  $V_{CC} = 6V$ ) because it is required that one programming pulse width does not exceed 78.75 ms at each address.

#### **ERASURE**

In order to clear all locations of their programmed contents, it is necessary to expose the MBM 27C512 to an ultraviolet light source. A dosage of 15 W-seconds/cm² is required to completely erase an MBM 27C512. This dosage can be obtained by exposure to an ultraviolet lamp (wavelength of 2537 Angstroms (Å)) with intensity of 12000µW/cm² for 15 to 21 minutes.

The MBM 27C512 should be about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the MBM 27C512 and similar devices, will erase with light sources having wavelengths shorter than 4000Å. Although erasure time will be much longer than

with UV source at 2537Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the MBM 27C512, and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package windows should be covered by an opaque label or substance.

#### **ELECTRONIC SIGNATURE**

The MBM 27C512 has electronic signature mode which is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its cor-

responding programming algorithm.

The electronic signature is activated when +12V is applied to address line A<sub>9</sub> (pin 24) of the MBM 27C512. Two identifier bytes are readed out from the

outputs by toggling address line  $A_0$  (pin 10) from  $V_{1L}$  to  $V_{1H}$ . The address lines from  $A_1$  to  $A_{13}$  must be hold at  $V_{1L}$  to keep the electronic signature mode. See the table below.

A <sub>0</sub>	01	O <sub>2</sub>	03	04	O <sub>5</sub>	06	07	O <sub>8</sub>	Definition
VIL	0	0	1	0	0	0	0	0	Manufacture
V <sub>IH</sub>	1	1	0	0	0	1	1	1	Device

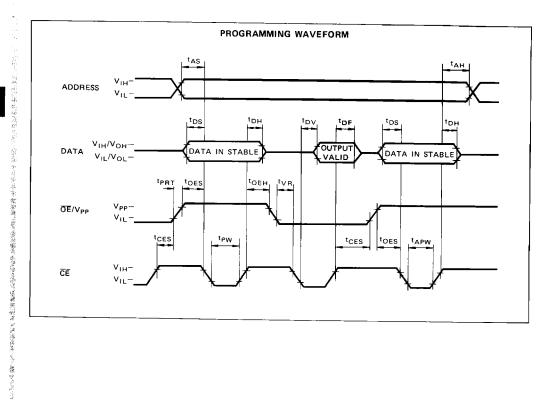
**Note:**  $A_9 = 12V \pm 0.5V$ 

 $A_1$  thru  $A_8 = A_{10}$  thru  $A_{13} = \overline{CE} = \overline{OE} = V_{1L}$ .

A14 = A15 = Either VIL or VIH



# PROGRAMMING/ERASING INFORMATION (Cont'd)



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#### DC CHARACTERISTICS

 $(T_A = 25\pm5^{\circ}C, V_{CC}^{*1} = 6V\pm0.25V, V_{PP}^{*2} = 12.5V\pm0.3V)$ 

		Value			Ulmia
Parameter	Symbol	Min	Тур	Max	Unit
Input Leakage Current (V <sub>IN</sub> = 5.25 V/0.45 V)	[iu]			10	μΑ
V <sub>PP</sub> Supply Current During Programming Pulse (CE = V <sub>IL</sub> )	Ірр			50	mA
V <sub>CC</sub> Supply Current	lcc			30	mA
Input Low Level	VIL	-0.1		0.8	V
Input High Level	V <sub>IH</sub>	2.0		V <sub>cc</sub> + 0.3	V
Output Low Voltage During Verify (I <sub>OL</sub> = 2.1 mA)	Vol			0.45	v
Output High Voltage During Verify (I <sub>OH</sub> = -400 µA)	V <sub>OH</sub>	2.4			٧

Note: \*1  $V_{CC}$  must be applied either coincidently or before  $V_{PP}$  and removed either coincidently or after  $V_{PP}$ .

<sup>\*2</sup> V<sub>PP</sub> must not be greater than 14 volts including overshoot. Permanent device damage may occur if the device is taken out or put into socket remaining V<sub>PP</sub> = 12.5 volts. Also, during  $\overline{CE}$  = V<sub>IL</sub>, V<sub>PP</sub> must not be switched from 5 to 12.5 volts or vice-versa.

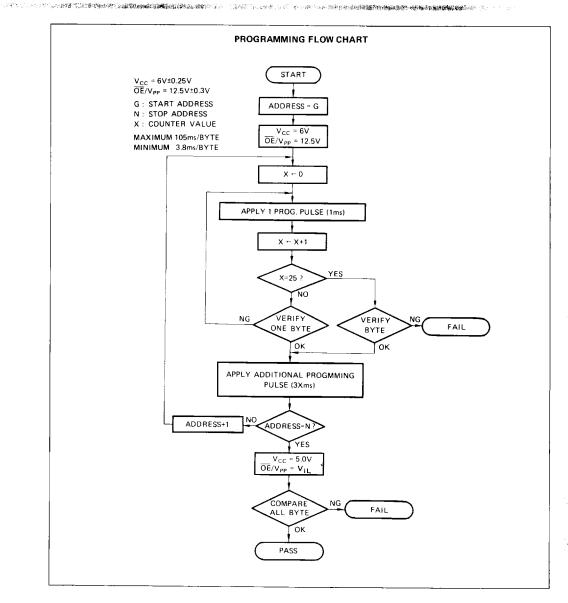
# PROGRAMMING/ERASING INFORMATION (Cont'd)

#### AC CHARACTERISTICS

 $\{T_A = 25\pm5^{\circ}C, V_{CC} = 6V\pm0.25V, V_{PP} = 12.5V\pm0.3V\}$ 

Parameter	Symbol	Min	Тур	Max	Unit
Address Setup Time	t <sub>AS</sub>	2			μs
Chip Enable Setup Time	t <sub>CES</sub>	2			μs
Output Enable Setup Time	t <sub>OES</sub>	2			μs
Data Setup Time	t <sub>DS</sub>	2			μs
V <sub>CC</sub> Setup Time	t <sub>VS</sub>	2			μs
Address Hold Time	t <sub>AH</sub>	2			μs
Data Hold Time	t <sub>DH</sub>	2	_		μs
Output Enable Hold Time	t <sub>OEH</sub>	2			μs
V <sub>PP</sub> Recovery Time	t <sub>VR</sub>	2			μs
Chip Enable to Data Valid	t <sub>DV</sub>			1	μs
Output Disable to Output Float Delay	t <sub>DF</sub>	0		130	ns
V <sub>PP</sub> Program Pulse Rise Time	t <sub>PRT</sub>	50			ns
Programming Pulse Width	t <sub>PW</sub>	0.95	1	1.05	ms
Additional Programming Pulse Width	t <sub>APW</sub>	2.85		78.75	ms

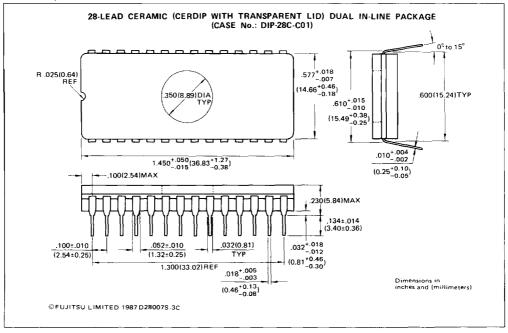
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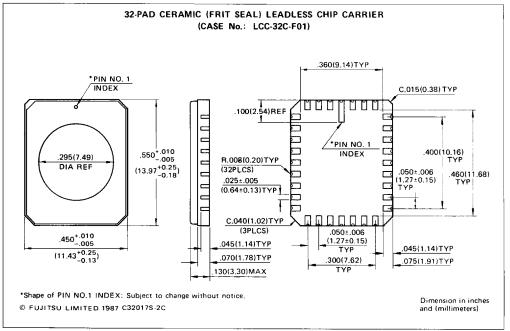
#### PACKAGE DIMENSIONS

Standard 28-pin Ceramic DIP (Suffix: -Z)



#### PACKAGE DIMENSIONS

Standard 32-pad Ceramic LCC (Suffix: -TV)



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